

RQ5H020SP

Pch -45V -2.0A Power MOSFET

V_{DSS}	-45V
$R_{DS(on)}(Max.)$	190m $Ω$
I _D	-2.0A
P_D	1.0W

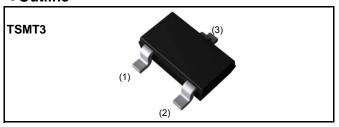
Features

- 1) Low on resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (TSMT3).
- 4) Pb-free lead plating; RoHS compliant

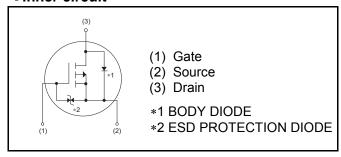
Application

DC/DC converters

Outline



•Inner circuit



Packaging specifications

		
	Packaging	Taping
	Reel size (mm)	180
Typo	Tape width (mm)	8
Type	Basic ordering unit (pcs)	3,000
	Taping code	TL
	Marking	FB

● Absolute maximum ratings(T_a = 25°C)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{ extsf{DSS}}$	-45	V
Continuous drain current	I _D *1	±2.0	А
Pulsed drain current	I _{D,pulse} *2	±8.0	А
Gate - Source voltage	V_{GSS}	±20	V
Power dissipation	P _D *3	1.0	W
rowei dissipation	P _D *4	0.54	W
Junction temperature	T _j	150	°C
Range of storage temperature	T _{stg}	−55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
r arameter	Symbol	Min.	Тур.	Max.	Offic
Thormal resistance junction, ambient	R _{thJA} *3	-	-	125	°C/W
Thermal resistance, junction - ambient	R _{thJA} *4	-	-	232	°C/W

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit	
r ai ai ii e tei	1 arameter Symbol Conditions		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = -1mA$	-4 5	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = -1mA referenced to 25°C	1	-43	1	mV/°C	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -45V, V_{GS} = 0V$	ı	-	-1	μΑ	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	ı	-	±10	μА	
Gate threshold voltage	V _{GS (th)}	$V_{DS} = -10V, I_{D} = -1mA$	-1.0	-	-3.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{(GS)th}}{\Delta T_{j}}$	I _D = -1mA referenced to 25°C	1	3.2	-	mV/°C	
		V_{GS} = -10V, I_{D} = -2.0A	-	130	190		
Static drain - source	$R_{DS(on)}^{}}$	V_{GS} = -4.5V, I_{D} = -2.0A	-	180	260	m()	
on - state resistance		V_{GS} = -4.0V, I_{D} = -2.0A	-	200	280	mΩ	
		V_{GS} = -10V, I_D = -2.0A, T_j =125°C	1	200	ı		
Gate input resistannce	R_{G}	f = 1MHz, open drain	-	21	-	Ω	
Transconductance	9 fs *5	$V_{DS} = -10V, I_{D} = -2.0A$	1.2	4.0	-	S	

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 $\mu s,~Duty~cycle \leq$ 1%

^{*3} Mounted on a seramic board (30×30×0.8mm)

^{*4} Mounted on a FR4 (12×20×0.8mm)

^{*5} Pulsed

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	V _{GS} = 0V	-	500	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	80	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	40	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq -25V$, $V_{GS} = -10V$	-	8	-	
Rise time	t _r *5	$I_D = -1.0A$	-	10	-	no
Turn - off delay time	t _{d(off)} *5	$R_L = 25\Omega$	-	35	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	10	-	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	${\sf Q_g}^{^{*5}}$	$V_{DD}^{\sim} -25V$, $I_{D} = -2.0A$ $V_{GS} = -4.5V$	-	4.5	-	
rotal gate charge	Q _g °	$V_{DD}^{\sim} -25V, I_{D} = -2.0A$ $V_{GS} = -10V$	-	9.5	-	nC
Gate - Source charge	Q _{gs} *5	$V_{DD}^{\sim} -25V, I_{D} = -2.0A$ $V_{GS} = -10V$	-	1.6	-	
Gate - Drain charge	Q _{gd} *5	$V_{GS} = -10V$	1	1.2	-	

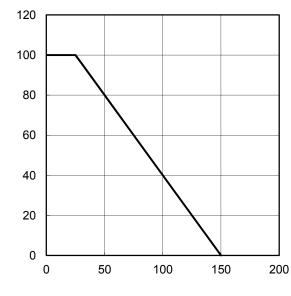
•Body diode electrical characteristics (Source-Drain)($T_a = 25$ °C)

Parameter	Symbol Conditions -		Values			Unit
r ai ainetei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l _S *1	T _a = 25°C	-	-	-0.8	А
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_s = -2.0A$	-	-	-1.2	V

Power Dissipation: P_D/P_D max. [%]

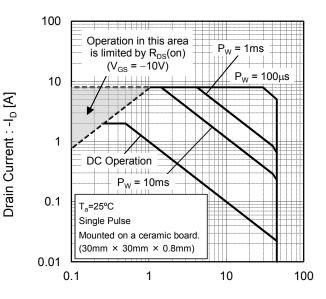
• Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

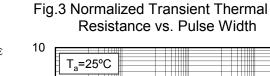


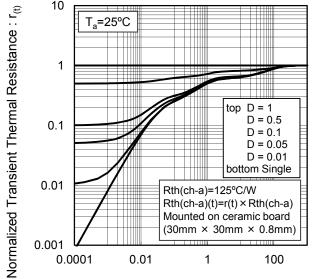
Junction Temperature : Tj [°C]

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V_{DS} [V]



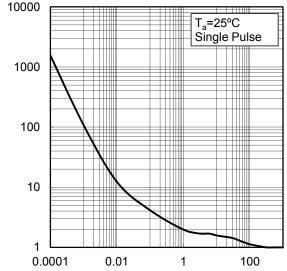


Pulse Width: Pw [s]

Fig.4 Single Pulse Maxmum Power dissipation

10000

T_a=25°C
Single Pulse



Pulse Width : P_W [s]

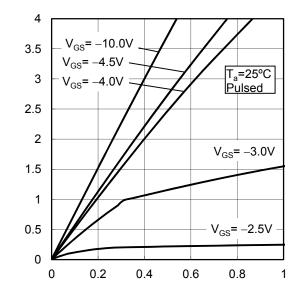
Peak Transient Power: P(W)

Drain Current: -l_D [A]

Drain - Source Breakdown Voltage : - $V_{(BR)DSS}$ [V]

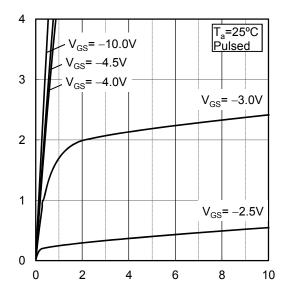
• Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



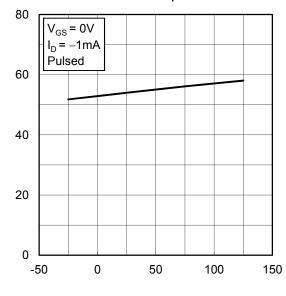
Drain - Source Voltage : -V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



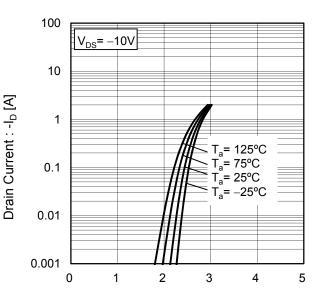
Drain - Source Voltage : -V_{DS} [V]

Fig.7 Breakdown Voltage vs. Junction Temperature



Junction Temperature : T_i [°C]

Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : -V_{GS} [V]

Drain Current: -l_D [A]

Gate Threshold Voltage: -V_{GS(th)} [V]

•Electrical characteristic curves

Fig.9 Gate Threshold Voltage

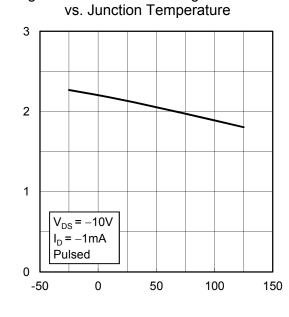
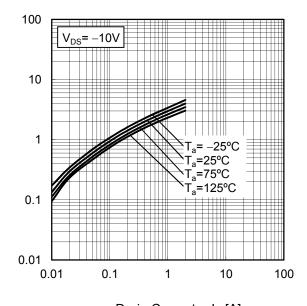


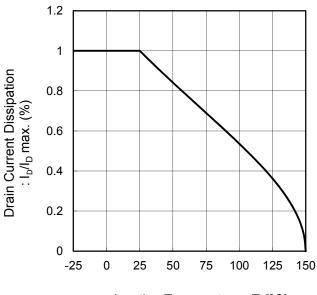
Fig.10 Transconductance vs. Drain Current



Junction Temperature : T_i [°C]

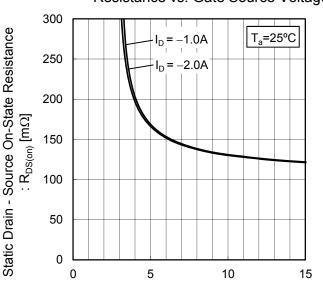
Drain Current : -I_D [A]

Fig.11 Drain CurrentDerating Curve



Junction Temperature : T_i [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Gate - Source Voltage : -V_{GS} [V]

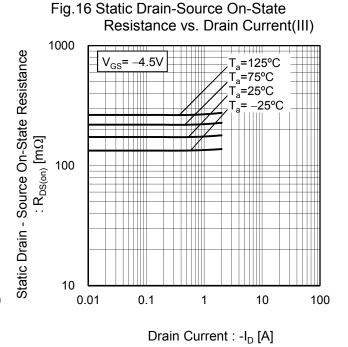
Transconductance: g_{fs} [S]

• Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I) 1000 Static Drain - Source On-State Resistance T₂=25°C V_{GS}= -4.0V V_{GS}= -4.5V -10V $:R_{\text{DS(on)}}\left[m\Omega \right]$ 100 10 0.01 0.1 1 10 100 Drain Current : -I_D [A]

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature 250 Static Drain - Source On-State Resistance 200 150 $:R_{\text{DS(on)}}\left[\text{m}\Omega\right]$ 100 50 $V_{GS} = -10V$ $I_{D} = -2.0A$ Pulsed 0 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T_i [°C]

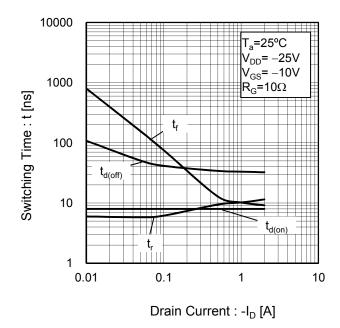
Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II) 1000 Static Drain - Source On-State Resistance =125°C T_a=75°C Ta=25°C -25°C $: R_{DS(on)} \left[m\Omega \right]$ 100 10 0.01 0.1 1 10 100 Drain Current : -I_D [A]



• Electrical characteristic curves

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV) 1000 Static Drain - Source On-State Resistance -4.0V=75°C 25°C -25°C $:R_{\text{DS(on)}}\left[\text{m}\Omega \right]$ 100 10 0.01 0.1 1 10 100 Drain Current : -I_D [A]

Fig.19 Switching Characteristics



Gate - Source Voltage : - V_{GS} [V]

0 2

10 $T_a=25^{\circ}C$ $V_{DD}=-25V$ $V_{DD}=2A$ $V_{DD}=2A$

Fig.20 Dynamic Input Characteristics

Drain - Source Voltage : - V_{DS} [V]

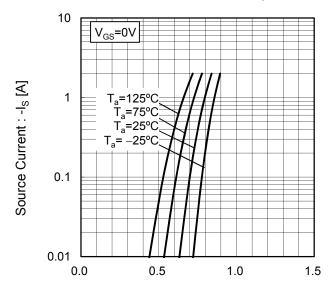
Total Gate Charge : Q_g [nC]

5

10

•Electrical characteristic curves

Fig.21 Source Current vs. Source Drain Voltage



Source-Drain Voltage : - V_{SD} [V]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

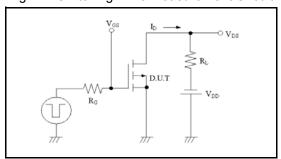


Fig.2-1 Gate Charge Measurement Circuit

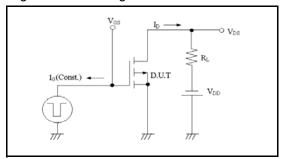


Fig.1-2 Switching Waveforms

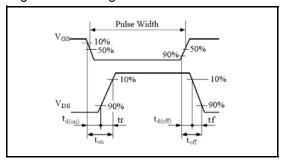
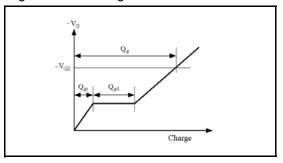
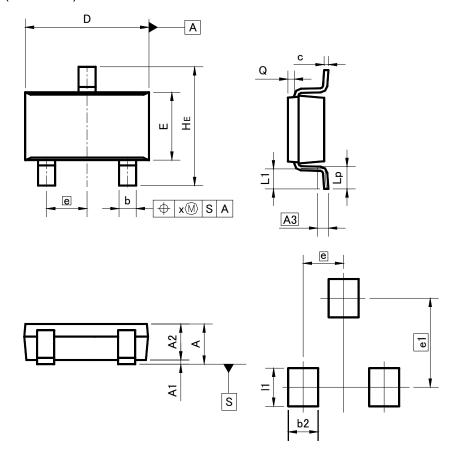


Fig.2-2 Gate Charge Waveform



●Dimensions (Unit : mm)





Patterm of terminal position areas

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	_	1.00	ı	0.039
A1	0.00	0.10	0	0.004
A2	0.75	0.95	0.03	0.037
A3	0.3	25	0.0	01
b	0.35	0.50	0.014	0.02
С	0.10	0.26	0.004	0.01
D	2.80	3.00	0.11	0.118
Е	1.50	1.80	0.059	0.071
е	0.9	95	0.0	04
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.01
х	_	0.20		0.008

DIM	MILIMI	ETERS	INC	HES
INITO	MIN	MAX	MIN	MAX
e1	2.	2.10 0.08		08
b2		0.70	_	0.028
l1	_	0.90	_	0.035

Dimension in mm/inches

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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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